Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier in a SOT1292(IITO3P) plastic package intended for use in applications requiring very high inrush current capability and high thermal cycling performance. It is used in applications where "high junction operating temperature capability" ($T_{i(max)} = 150$ °C) is required.

2. Features and benefits

- · High thermal cycling performance
- · Planar passivated for voltage ruggedness and reliability
- · High voltage capacity
- Very high current surge capability
- Insulated tab rated at 2500 V rms
- High junction operating temperature capability (T_{i(max)} = 150 °C)

3. Applications

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- · Lighting and temperature control
- Uninterruptible Power Supply (UPS)
- Solid State Relay (SSR)
- Traction battery charging
- Applications subject to high temperature ($T_{i(max)} = 150 \, ^{\circ}C$)

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DRM}	repetitive peak off- state voltage		-	-	1200	V
V_{RRM}	repetitive peak reverse voltage		-	-	1200	V
	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5	-	-	650	Α
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms	-	-	715	Α
Tj	junction temperature		-	-	150	°C
I _{T(AV)}	average on-state current	half sine wave; T _{mb} ≤ 73 °C	-	-	50	Α
I _{T(RMS)}	RMS on-state current	half sine wave; $T_{mb} \le 73 \text{ °C}$; $\overline{Fig. 1}$; $\overline{Fig. 2}$; $\overline{Fig. 3}$	-	-	79	Α

Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
Static characte	eristics							
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7; Fig. 8}$		-	-	50	mA	
Dynamic chara	Dynamic characteristics							
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 800 V; T_j = 125 °C; R_{GK} = 100 Ω; $(V_{DM}$ = 67% of V_{DRM}); exponential waveform		1500	-	-	V/µs	

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		A - [
2	А	anode		G sym037
3	G	gate	0	Symoon
mb	n.c.	mounting base; isolated		
			IITO3P (SOT1292)	

6. Ordering information

Table 3. Ordering information

Table 3. Ordering init	Table 3. Ordering information						
Type number	Package						
	Name	Description	Version				
BT155Z-1200T	IITO3P	plastic single-ended through-hole package; isolated heatsink mounted; 1 mounting hole; 3-lead TO3P	SOT1292				

7. Marking

Table 4. Marking codes

Type number	Marking code
BT155Z-1200T	BT155Z-1200T

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	1200	V
V_{RRM}	repetitive peak reverse voltage		-	1200	V
I _{T(AV)}	average on-state current	half sine wave; T _{mb} ≤ 73 °C	-	50	Α
I _{T(RMS)}	RMS on-state current	half sine wave; $T_{mb} \le 73 ^{\circ}\text{C}$; Fig. 1; Fig. 2; Fig. 3	-	79	Α
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5	-	650	Α
		half sine wave; T _{j(init)} = 25 °C; t _p = 8.3 ms	-	715	Α
l ² t	I ² t for fusing	t _p = 10 ms; sine-wave pulse	-	2113	A²s
dl _T /dt	rate of rise of on-state current	I _G = 200 mA	-	150	A/µs
I _{GM}	peak gate current		-	8	Α
V_{RGM}	peak reverse gate voltage		-	5	V
P_{GM}	peak gate power		-	20	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	1	W
T _{stg}	storage temperature		-40	150	°C
Tj	junction temperature		-	150	°C

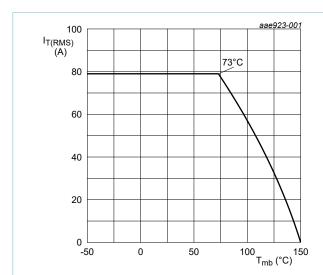
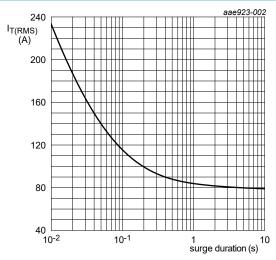


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



 $f = 50 \text{ Hz}; T_{mb} = 73 \text{ }^{\circ}\text{C}$

Fig. 2. RMS on-state current as a function of surge duration; maximum values

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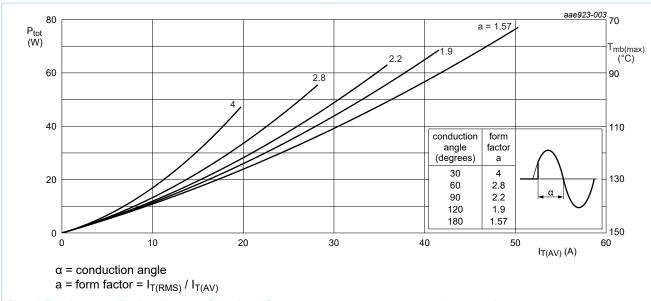


Fig. 3. Total power dissipation as a function of average on-state current; maximum values

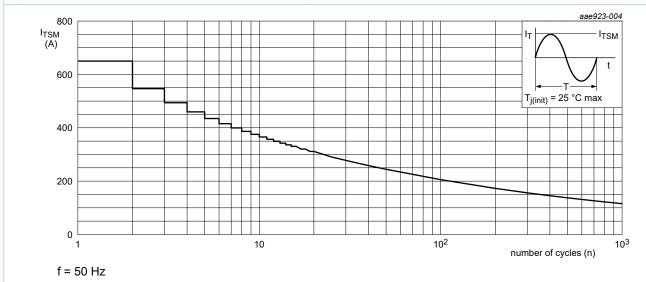
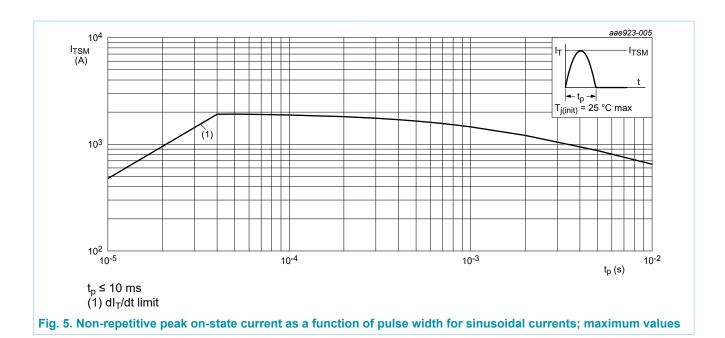


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

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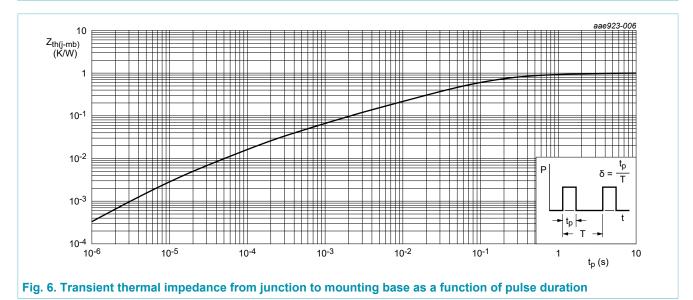
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9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	full cycle; Fig. 6	-	-	1	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	in free air	-	50	-	K/W



10. Isolation characteristics

Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol} (RMS)	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; $50 \text{ Hz} \le f \le 60 \text{ Hz}$; $RH \le 65 \%$; $T_{mb} = 25 \text{ °C}$	-	-	2500	V

11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static char	acteristics					,
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7; Fig. 8}$	-	-	50	mA
IL	latching current	V _D = 12 V; I _G = 0.1 A; T _j = 25 °C; <u>Fig. 9</u>	-	-	300	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 10</u>	-	-	200	mA
V _T	on-state voltage	I _T = 50 A; T _j = 25 °C; <u>Fig. 11</u>	-	-	1.3	V
		I _T = 90 A; T _j = 25 °C; <u>Fig. 11</u>	-	-	1.5	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$ Fig. 12	-	0.7	1	V
		$V_D = 800 \text{ V}; I_T = 0.1 \text{ A}; T_j = 125 \text{ °C};$ Fig. 12	0.25	0.4	-	V
I _D	off-state current	V _D = 1200 V; T _j = 125 °C -		-	3	mA
I _R	reverse current	V _R = 1200 V; T _j = 125 °C	-	-	3	mA
Dynamic cl	haracteristics				'	
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 800 V; T_j = 125 °C; R_{GK} = 100 Ω ; $(V_{DM}$ = 67% of V_{DRM}); exponential waveform	1500	-	-	V/µs
		V_{DM} = 800 V; T_{j} = 150 °C; R_{GK} = 100 Ω ; $(V_{DM}$ = 67% of V_{DRM}); exponential waveform	1000	-	-	V/µs
t _{gt}	gate-controlled turn-on time	urn-on $I_{TM} = 40 \text{ A}; V_D = 800 \text{ V}; I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu\text{s}; T_i = 25 °C$		2	-	μs
t _q commutated turn-off time		$\begin{array}{l} V_{DM} = 804 \text{ V; } T_j = 125 \text{ °C; } I_{TM} = 20 \text{ A;} \\ V_R = 25 \text{ V; } (dI_T/dt)_M = 30 \text{ A/µs; } dV_D/\\ dt = 50 \text{ V/µs; } R_{GK(ext)} = 100 \text{ k}\Omega; \text{ (V}_{DM} = 67\% \text{ of V}_{DRM}) \end{array}$	-	150	-	μs

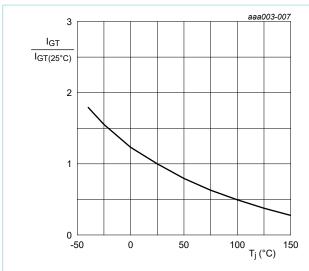


Fig. 7. Normalized gate trigger current as a function of junction temperature

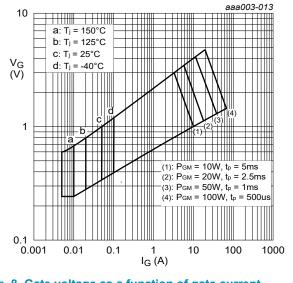


Fig. 8. Gate voltage as a function of gate current

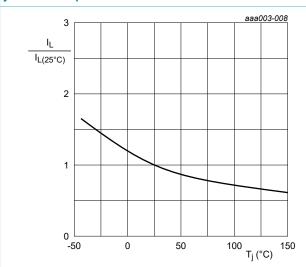


Fig. 9. Normalized latching current as a function of junction temperature

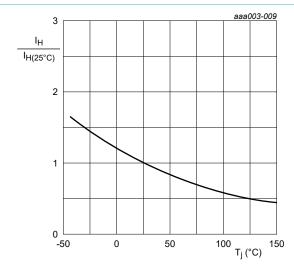
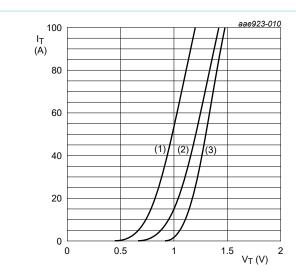


Fig. 10. Normalized holding current as a function of junction temperature

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 $V_o = 0.974 \text{ V}; R_s = 0.0045 \Omega$

(1) T_j = 150 °C; typical values (2) T_j = 150 °C; maximum values

(3) T_j = 25 °C; maximum values

Fig. 11. On-state current as a function of on-state voltage

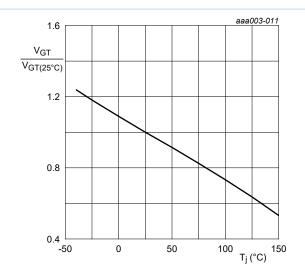
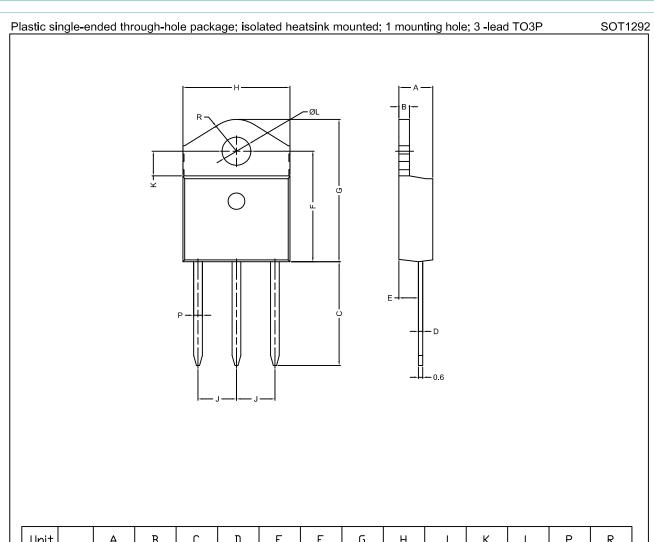


Fig. 12. Normalized gate trigger voltage as a function of junction temperature

12. Package outline



Unit		Α	В	С	D	Ε	F	G	н	J	K	L	Р	R
mm	min	4.75	1.45	14.35	0.50	2.70	15.80	20.40	15.10	5,40	3.40	4.08	1.20	4.6
1111	max	4.95	1.55	15.60	0.70	2.90	16.50	21.10	15.50	5.65	3.65	4.17	1.40	(typ.)

OUTLINE		REFEREN	CES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT1292		-			

Fig. 13. Package outline IITO3P (SOT1292)

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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